

Part Number: **1N5819HW-(p)-F**
Weight (mg): 10.73694

p = package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	3.23	0.3464	1000000	32262
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	27.90	2.99544	576500	160835
		Ni	7440-02-0	41.00%			410000	114384
		Mn	7439-96-5	0.60%			6000	1674
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	279
		Co	7440-48-4	0.50%			5000	1395
		Si	7440-21-3	0.15%			1500	418
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.85	0.0909	1000000	8466
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.04	0.1114	1000000	10375
Encapsulation	KTMC1050G	Silicone dioxide	60676-86-0	69.00%	63.69	6.8381	690000	439444
		Ortho Creson Novolac Epoxy Resin	29690-82-2	12.25%			122500	78017
		Basic Durometer:Phenolic resin (Compound of polymeric network)	9003-35-4	5.50%			55000	35028
		Misc.	system	12.75%			127500	81202
		Carbon black	1333-86-4	0.50%			5000	3184
Die attach epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	1.32	0.1412	750000	9863
		epoxy resin	Trade secret	20.00%			200000	2630
		curing agent & hardener	Trade secret	5.00%			50000	658
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.99	0.2135	1000000	19885
				Total	100.00	10.73694		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos

Azo compounds

Cadmium and cadmium compounds

Certain Shortchain Chlorinated Paraffins

Chlorinated organic compounds

Hexavalent chromium compounds

Lead and lead compounds

Mercury and mercury compounds

Organic tin compounds

Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)

Ozone Depleting Substances - Class II (HCFCs)

Perfluorooctane Sulphonate (PFOS) or related compounds

Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**

Polychlorinated Biphenyls (PCBs)

Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Tributyl Tin Oxide (TBTO)